

Schottky Diode

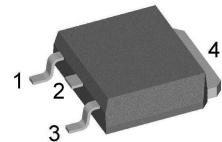
V_{RRM} = 200 V
 I_{FAV} = 15 A
 V_F = 0.78 V

High Performance Schottky Diode
 Low Loss and Soft Recovery
 Single Diode

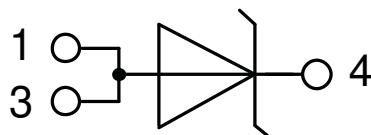
Part number

DSA15IM200UC

Marking on Product: SFMAUI



Backside: cathode



Features / Advantages:

- Very low V_F
- Extremely low switching losses
- Low I_{rm} values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package: TO-252 (DPak)

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

Disclaimer Notice

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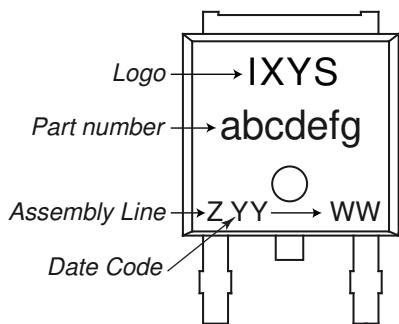
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Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			200	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			200	V
I_R	reverse current, drain current	$V_R = 200 V$ $V_R = 200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		250 2.5	μA mA
V_F	forward voltage drop	$I_F = 15 A$ $I_F = 30 A$ $I_F = 15 A$ $I_F = 30 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.94 1.10 0.78 0.95	V V
I_{FAV}	average forward current	$T_C = 150^\circ C$ rectangular $d = 0.5$	$T_{VJ} = 175^\circ C$		15	A
V_{F0} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ C$		0.53 10.8	V $m\Omega$
R_{thJC}	thermal resistance junction to case				2	K/W
R_{thCH}	thermal resistance case to heatsink			0.50		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		75	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}; V_R = 0 V$	$T_{VJ} = 45^\circ C$		200	A
C_J	junction capacitance	$V_R = 24 V$ f = 1 MHz	$T_{VJ} = 25^\circ C$		67	pF

Package TO-252 (DPak)

Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal ¹⁾			20	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				0.3		g
F_c	mounting force with clip		20		60	N

¹⁾ I_{RMS} is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.

Product Marking

Part description

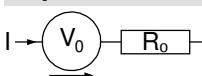
D = Diode
S = Schottky Diode
A = low VF
15 = Current Rating [A]
IM = Single Diode
200 = Reverse Voltage [V]
UC = TO-252AA (DPak)

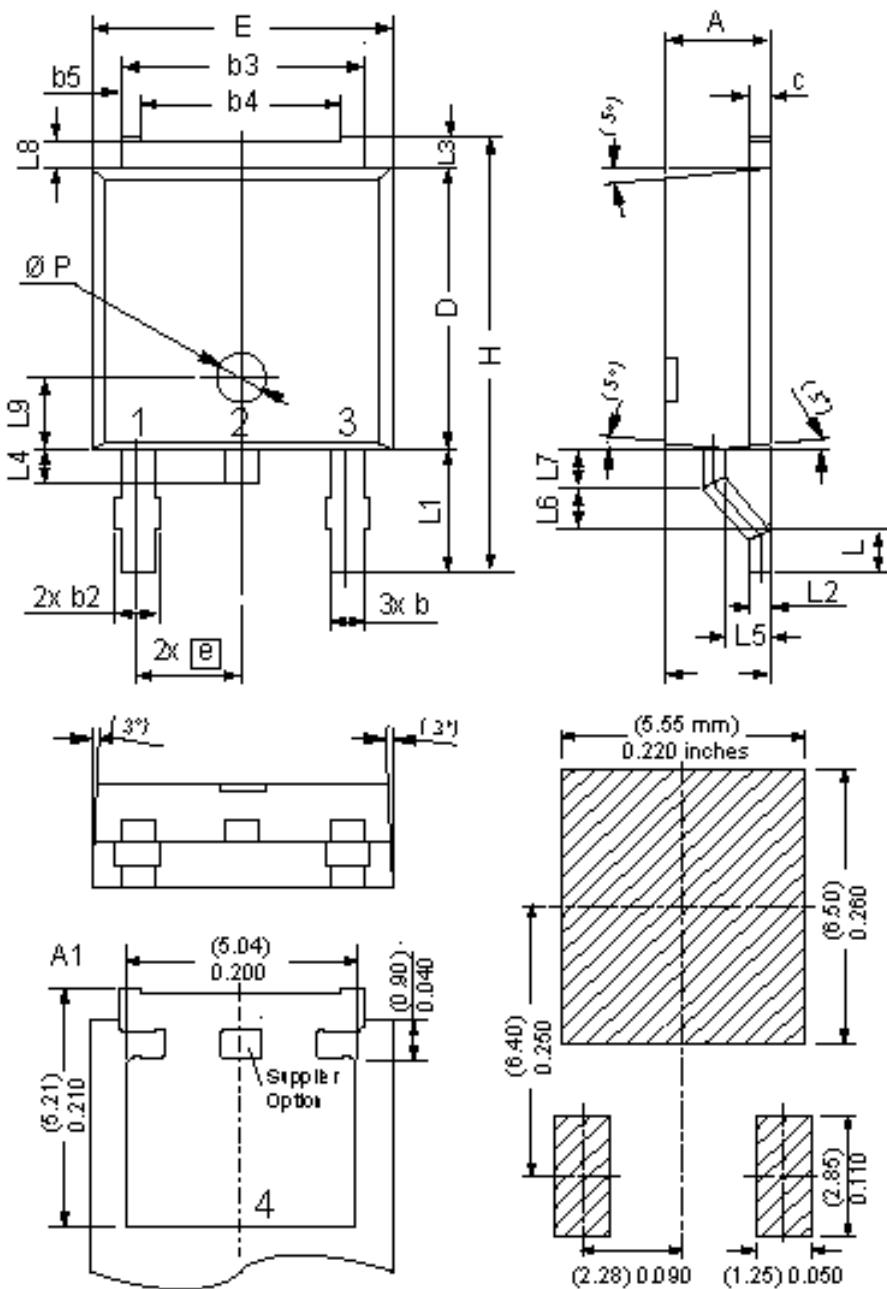
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSA15IM200UC-TRL	SFMAUI	Tape & Reel	2500	510408
Alternative	DSA15IM200UC-TUB	SFMAUI	Tube	70	523494

Similar Part	Package	Voltage class
DSB15IM30UC	TO-252AA (DPak)	30
DSA15IM45UC	TO-252AA (DPak)	45
DSA10IM100UC	TO-252AA (DPak)	100
DSA15IM150UC	TO-252AA (DPak)	150

Equivalent Circuits for Simulation
^{*} on die level

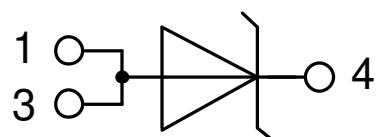
 $T_{VJ} = 175$ °C

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$V_{0\ max}$	threshold voltage	0.53 V
$R_{0\ max}$	slope resistance *	7.6 mΩ

Outlines TO-252 (DPak)


Dim.	Millimeters		Inches	
	min	max	min	max
A	2.20	2.40	0.087	0.094
A_1	2.10	2.50	0.083	0.098
b	0.66	0.86	0.026	0.034
b_2	-	0.96	-	0.038
b_3	5.04	5.64	0.198	0.222
b_4	4.34 BSC	4.34 BSC	0.171 BSC	0.171 BSC
b_5	0.50 BSC	0.50 BSC	0.020 BSC	0.020 BSC
c	0.40	0.86	0.016	0.034
D	5.90	6.30	0.232	0.248
E	6.40	6.80	0.252	0.268
e	2.10	2.50	0.083	0.098
H	9.20	10.10	0.362	0.398
L	0.55	1.28	0.022	0.050
L_1	2.50	2.90	0.098	0.114
L_2	0.40	0.60	0.016	0.024
L_3	0.50	0.90	0.020	0.035
L_4	0.60	1.00	0.024	0.039
L_5	0.82	1.22	0.032	0.048
L_6	0.79	0.99	0.031	0.039
L_7	0.81	1.01	0.032	0.040
L_8	0.40	0.80	0.016	0.031
L_9	1.50 BSC	1.50 BSC	0.059 BSC	0.059 BSC
$\emptyset P$	1.00 BSC	1.00 BSC	0.039 BSC	0.039 BSC

Recommended
min. foot print



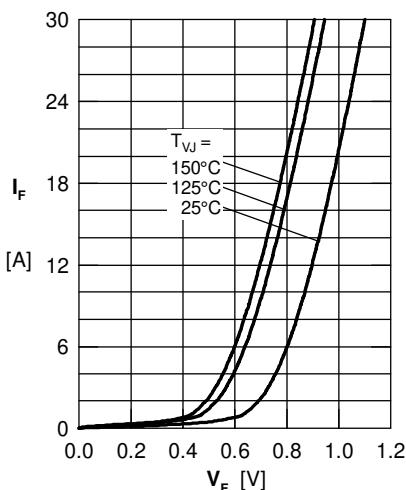
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Fig. 1 Maximum forward voltage drop characteristics

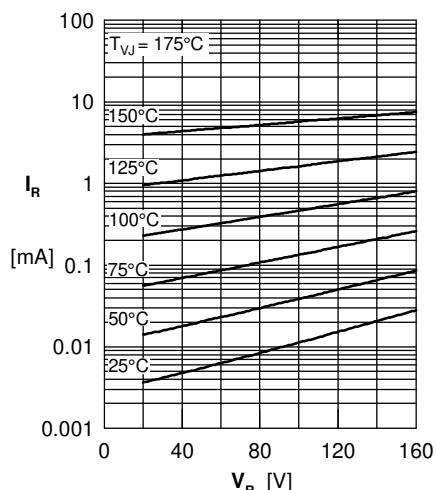


Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R

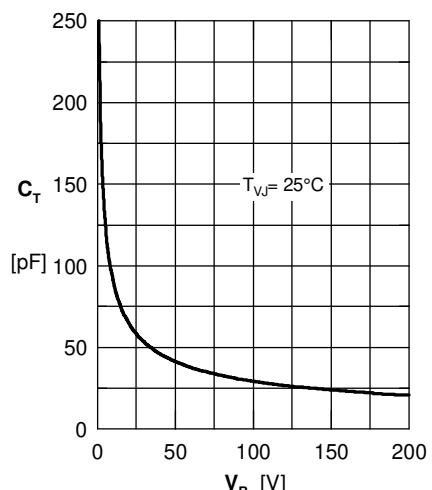


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

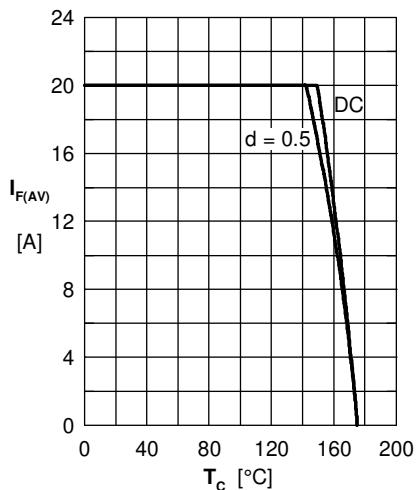


Fig. 4 Avg: forward current $I_{F(AV)}$ vs. case temperature T_C

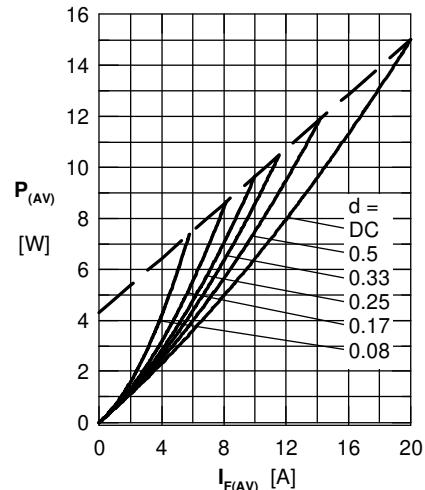


Fig. 5 Forward power loss characteristics

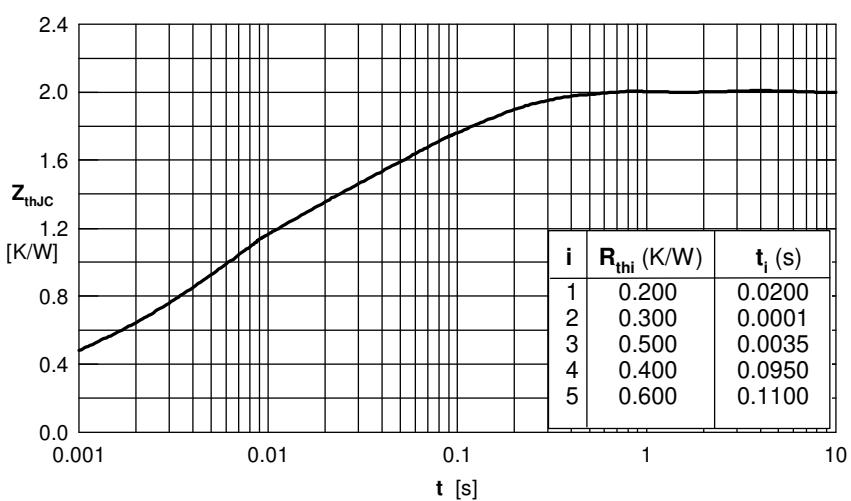


Fig. 6 Transient thermal impedance junction to case